

HWG38Z89Y-80

Description

The HWG38Z89Y-80 is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.

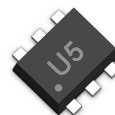
Feature

- u 100 Watts Peak Pulse Power per Line (tp=8/20μs)
- u Protects up to four / five I/O lines
- u Ultra-small package (1.6X1.6X0.55mm), requires less than 2.9mm² of PCB area
- u Working voltages : 5V
- u Low leakage current
- u IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- u IEC61000-4-4 (EFT) 40A (5/50ns)

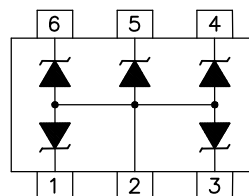
Applications

- u Cellular Handsets & Accessories
- u Cordless Phones
- u Personal Digital Assistants (PDA's)
- u Portable Instrumentation
- u Notebooks & Handhelds
- u Digital Cameras
- u MP3 Players

SOT-563



Functional Diagram



Mechanical Characteristics

- u JEDEC SOT-563 Package
- u Molding Compound Flammability Rating : UL 94V-0
- u Weight 3.0 Milligrams (Approximate)
- u Quantity Per Reel : 3,000pcs
- u Reel Size : 7 inch
- u Lead Finish : Lead Free

Mechanical Characteristics

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (tp=8/20μs waveform)	100	W
T _L	Lead Soldering Temperature	260 (10sec)	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
T _J	Operating Temperature Range	-55 to +150	°C
	IEC61000-4-2 (ESD)		
	Air Discharge	±15	KV
	Contact Discharge	±8	
	IEC61000-4-4 (EFT)	40	A

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Electrical Characteristics (@ 25°C Unless Otherwise Specified)

Part Number	Device Marking	V _{RWM} (V) (Max.)	V _B (V) (Min.)	I _T (mA)	V _C @1A (Max.)	V _C		I _R (μA) (Max.)	C (pF) (Typ.)
						(Max.)	(@A)		
HWG38Z89Y-80	U5	5	6	1	9.8	12	5	1	30

Characteristic Curves

Fig1. 8/20μs Pulse Waveform

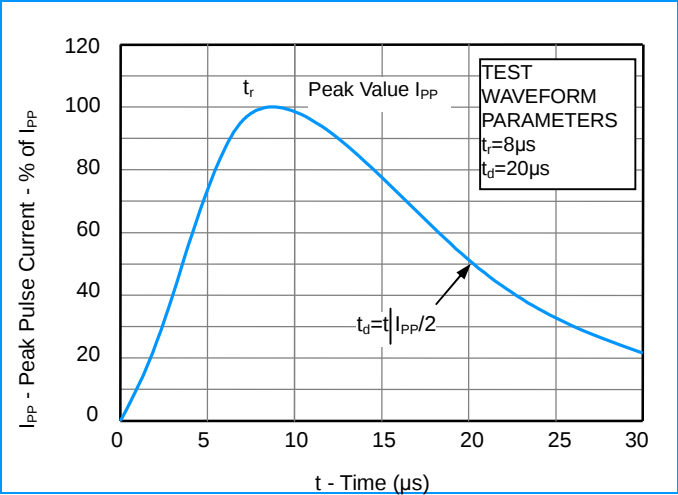


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

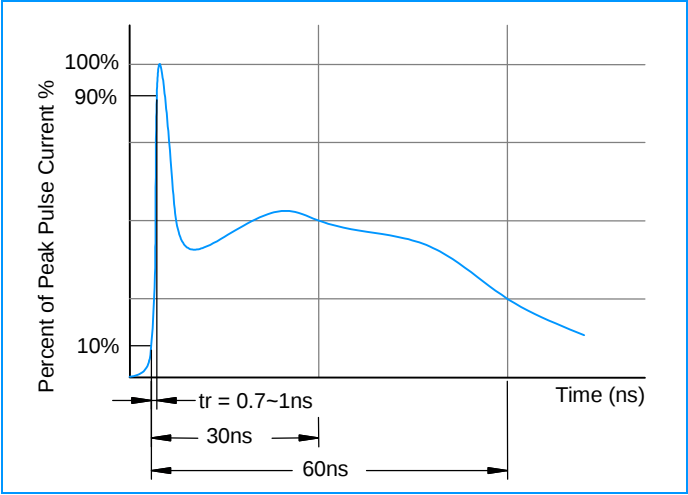
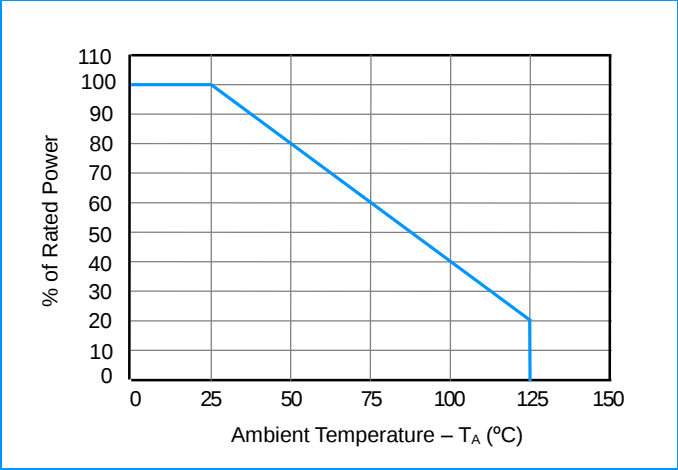


Fig3. Power Derating Curve



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Characteristic Curves

Fig4. ESD Clamping (+8KV Contac per IEC61000-4-2)

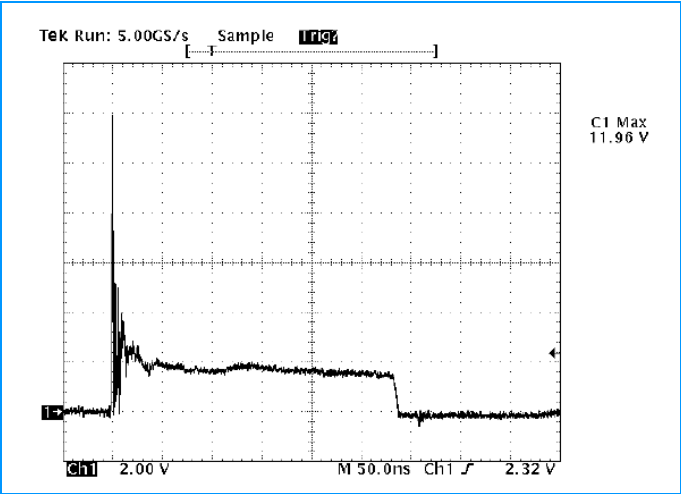
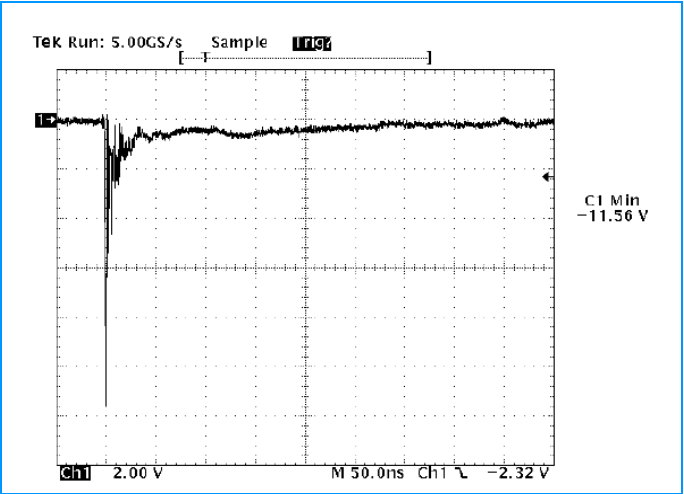
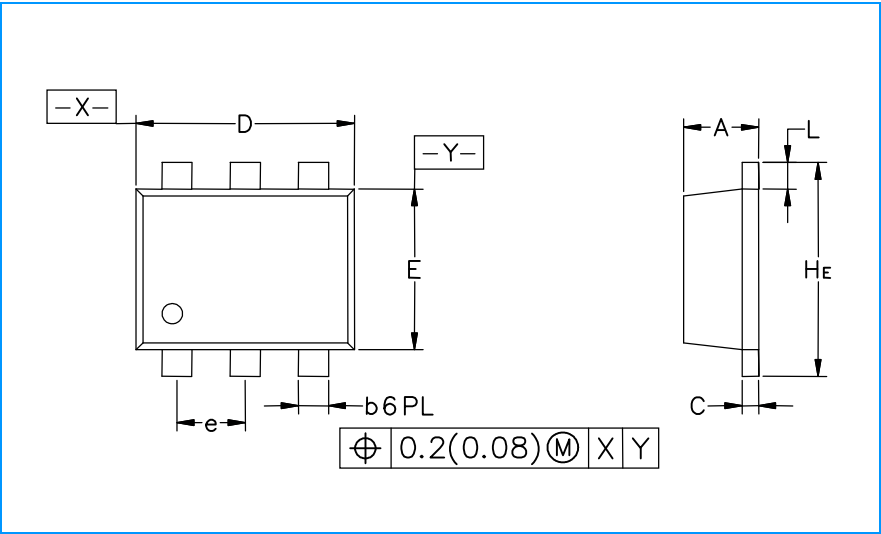


Fig5. ESD Clamping (-8KV Contac per IEC61000-4-2)

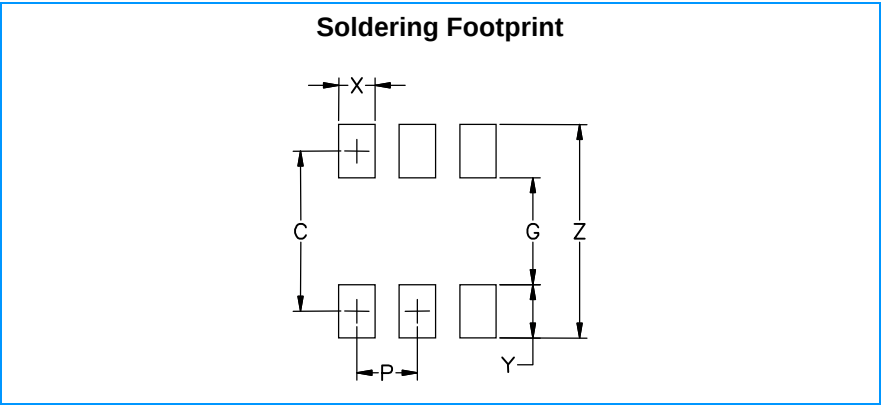


SOT-363 Package Outline & Dimensions



Symbol	Inches			Millimeters		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.020	0.021	0.023	0.50	0.55	0.60
b	0.007	0.009	0.011	0.17	0.22	0.27
C	0.003	0.005	0.007	0.08	0.12	0.18
D	0.059	0.062	0.066	1.50	1.60	1.70
E	0.043	0.047	0.051	1.10	1.20	1.30
e	0.02 BSC			0.5 BSC		
L	0.004	0.008	0.012	0.10	0.20	0.30
H _E	0.059	0.062	0.067	1.50	1.60	1.70

Soldering Footprint



Symbol	Inches	Millimeters
C	0.0531	1.35
G	0.0354	0.90
P	0.0197	0.50
X	0.0118	0.30
Y	0.0177	0.45
Z	0.0709	1.80